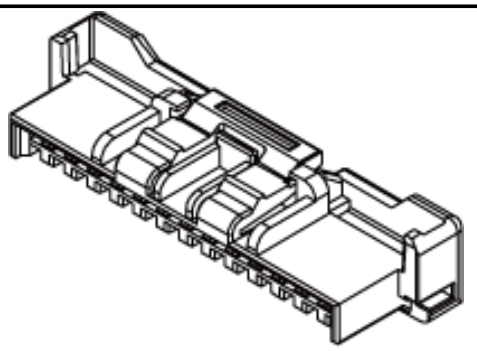
This document was generated on 01/06/2009

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 5024391400

Status: Active

Description: 2.00mm (.079") Pitch CLIK-Mate™ Wire-to-Board Housing, Single Row, Positive Lock, 14 Circuits



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Product Specification PS-502443-001 (PDF)
Related Catalog Page (PDF)

General

Product Family	Crimp Housings
Series	502439
Product Name	CLIK-Mate™

Physical

Breakaway	No
Circuits (maximum)	14
Color - Resin	White
Gender	Plug
Keying to Mating Part	Yes
Lock to Mating Part	Yes
Number of Rows	1
Packaging Type	Bag
Panel Mount	No
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Polarized to Mating Part	Yes
Stackable	No
Temperature Range - Operating	-25°C to +85°C

Material Info

Reference - Drawing Numbers

Product Specification	PS-502443-001
Sales Drawing	SD-502439-002

EU RoHS
ELV and RoHS Compliant

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
502439 Series

Mates With
502443 PCB Receptacle Vertical . 502494 PCB Receptacle Right Angle

Use With
502438 Crimp Terminal

This document was generated on 01/06/2009

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

REV.	REV. RECORD	DATE	EC NO.	WRITTEN:	CH'K:
A	PROPOSED	'07/05/18	J2007-2645	N.ITO	K.ASAKAWA
B	REVISED	'07/05/29	J2007-3240	N.ITO	K.ASAKAWA
C	REVISED	'07/07/20	J2008-0216	N.ITO	K.ASAKAWA
D	REVISED	'07/10/16	J2008-1352	N.ITO	K.ASAKAWA
E	REVISED	'07/12/21	J2008-2504	Y.GOTO	K.ASAKAWA

REVISE ON PC ONLY

REV.	DESCRIPTION
E	SEE SHEET 1

TITLE:
2.0mm PITCH WIRE TO BOARD CONNECTOR
SINGLE TYPE
製品仕様書

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

４．実装後において手半田コテによるリペアーを行なう際は、必ず仕様書掲載の条件以内で行なって下さい。
条件を超えて実施した場合、端子の抜け、接点ギャップの変化、モールドの変形、溶融等が原因により
破損の原因になります。

Please conduct it under the condition of the specifications when repairing by hand soldering iron after mounting.
In the case of practicing beyond the condition, the backlash, the change in the contact gap,
the deformation of the mold and the melting, etc. may cause a damage.

５．弊社の推奨基板パターン寸法を変更して設計を行なう際は、致命的な不良の原因にもなりますので
あらかじめご相談下さい。

In the case of changing our recommended board pattern size and designing, please consult in advance
because it may cause a fatal defect.

６．リフロー条件によっては端子メッキ部にヨリ等が発生する場合がありますが、製品性能には影響は
ございません。

Strand, etc. may be generated on the terminal plating part according to the reflow condition, however,
there is no influence in the product performance.

７．リフロー条件によっては樹脂部に変色が発生する場合がありますが、製品性能には影響はございません。

Discoloration may be generated in the resin part according to the reflow condition, however,
there is no influence in the product performance.

８．半田上がりについて、「本コネクタは大気リフローでの実装を想定しています。N2リフローで実装
した場合、リフロー後、半田上がりを生じる恐れがあります。N2リフローでの実装をお考えの場合、
別途評価が必要になります。」

Soldering wicking: "This connector assumes the mounting by an air reflow. In the case of mounting
by the N2 reflow, there is a risk of the soldering wicking. The separate evaluation is necessary for
mounting by the N2 reflow."

９．推奨メタルマスク厚寸法及び開口率についての記載。又は、弊社評価では厚さT＝0.11mm、
開口率１００%のメタルマスクを使用しております。

Description of size of thickness of recommended metal mask and the aperture ratio.
And the metal mask of thickness of T=0.11mm and the aperture ratio of 100% is used in our evaluation.

THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO
MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION